



FQP7P06

60V P-Channel MOSFET

General Description

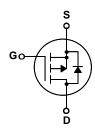
These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- -7A, -60V, $R_{DS(on)}$ = 0.41 Ω @V_{GS} = -10 V Low gate charge (typical 6.3 nC)
- Low Crss (typical 25 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP7P06	Units
V _{DSS}	Drain-Source Voltage		-60	V
I _D	Drain Current - Continuous (T _C = 25°	°C)	-7.0	Α
	- Continuous (T _C = 100°C)		-4.95	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	-28	Α
V_{GSS}	Gate-Source Voltage		± 25	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	90	mJ
I _{AR}	Avalanche Current	(Note 1)	-7.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-7.0	V/ns
P _D	Power Dissipation (T _C = 25°C)		45	W
	- Derate above 25°C		0.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.35	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu\text{A}$, Referenced to 25°C		-0.07		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -60 V, V _{GS} = 0 V			-1	μΑ
		V _{DS} = -48 V, T _C = 150°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-2.0		-4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -3.5 A		0.32	0.41	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -30 \text{ V}, I_D = -3.5 \text{ A}$ (Note 4)		4.0		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		225 110	295 145	pF pF
	' '	f = 1.0 MHz		_		
C _{rss}	Reverse Transfer Capacitance			25	32	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -30 \text{ V}, I_{D} = -3.5 \text{ A},$		7	25	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		50	110	ns
t _{d(off)}	Turn-Off Delay Time			7.5	25	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		25	60	ns
Qg	Total Gate Charge	$V_{DS} = -48 \text{ V}, I_{D} = -7.0 \text{ A},$		6.3	8.2	nC
Q_{gs}	Gate-Source Charge	V _{GS} = -10 V		1.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		3.1		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings	•			
I _S	Maximum Continuous Drain-Source Diode Forward Current				-7.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-28	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V, } I_{S} = -7.0 \text{ A}$			-4.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -7.0 \text{ A,}$		77		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 \text{ A/}\mu\text{s} \qquad \text{(Note 4)}$		0.23		μС

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.1 mH, I_{AS} = -7.0A, V_{DD} = -25V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq -7.0A, di/dt \leq 300A/us, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

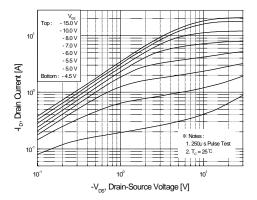


Figure 1. On-Region Characteristics

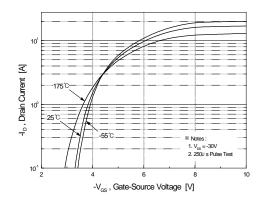


Figure 2. Transfer Characteristics

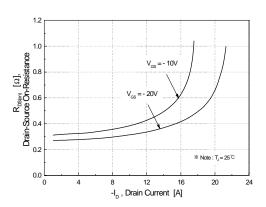


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

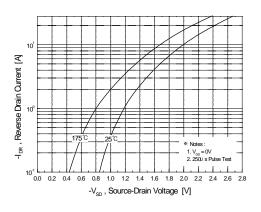


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

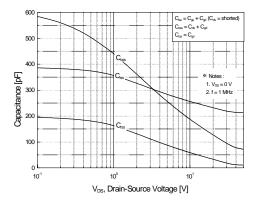


Figure 5. Capacitance Characteristics

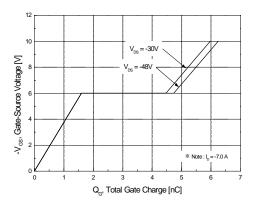
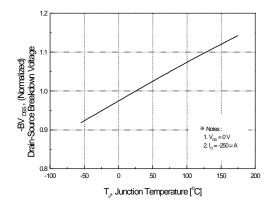


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



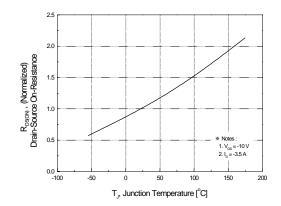
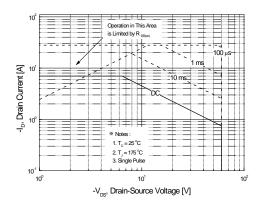


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



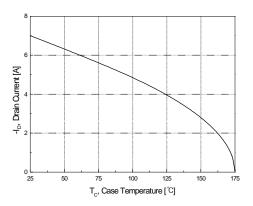


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

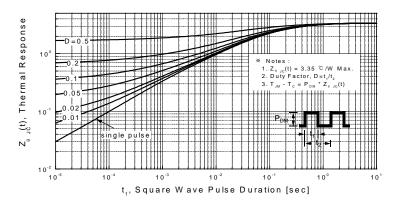
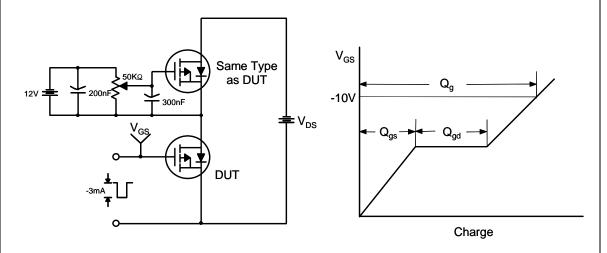


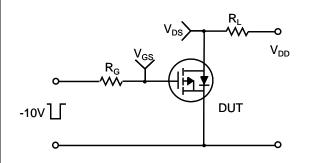
Figure 11. Transient Thermal Response Curve

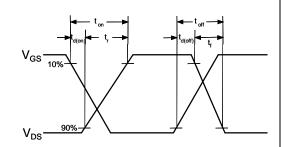
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Gate Charge Test Circuit & Waveform

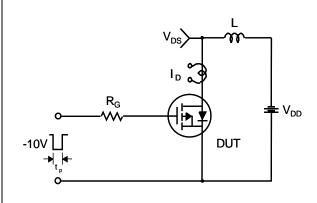


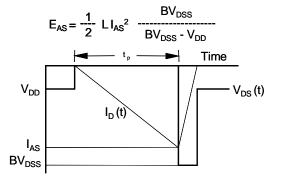
Resistive Switching Test Circuit & Waveforms



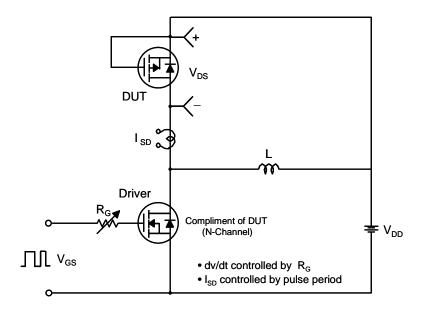


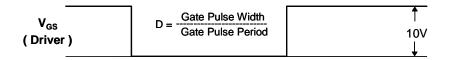
Unclamped Inductive Switching Test Circuit & Waveforms



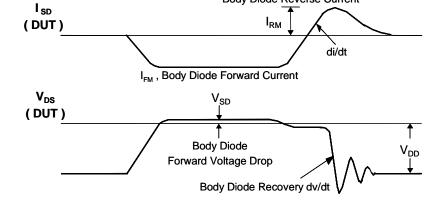


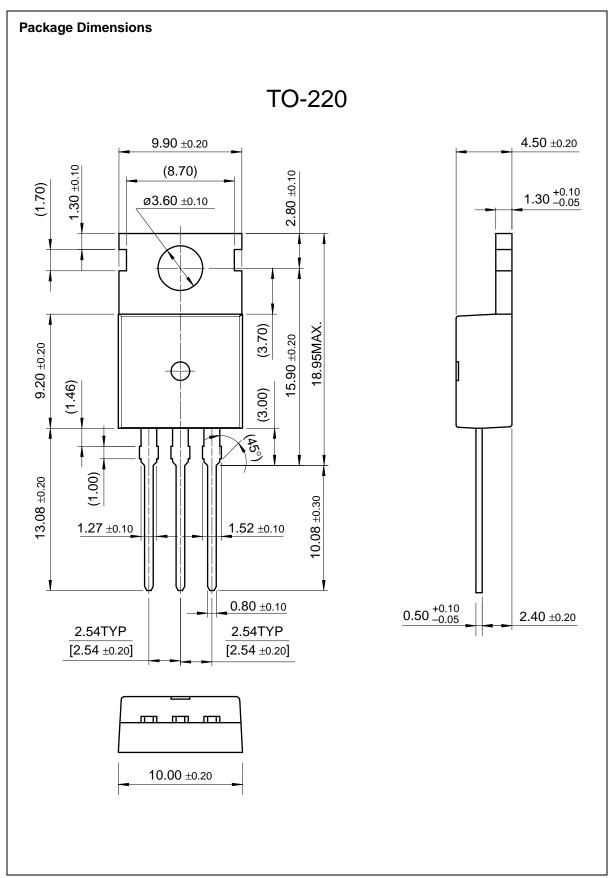
Peak Diode Recovery dv/dt Test Circuit & Waveforms





Body Diode Reverse Current





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